

Quad 2-Input NAND Schmitt Trigger

MM74HC132

General Description

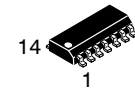
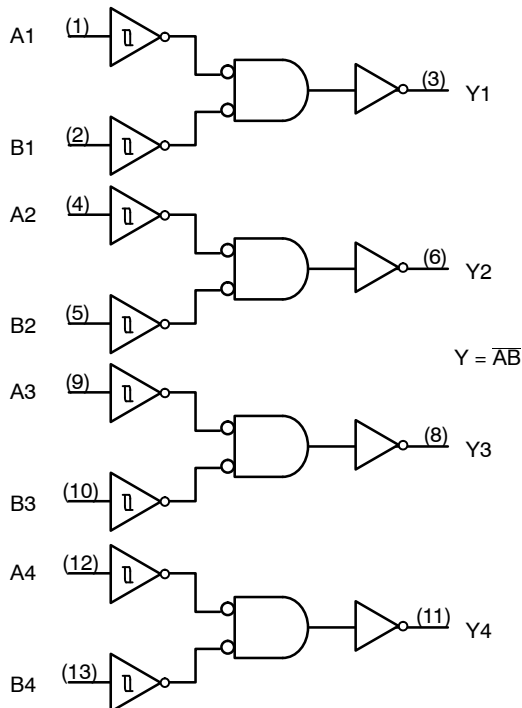
The MM74HC132 utilizes advanced silicon-gate CMOS technology to achieve the low power dissipation and high noise immunity of standard CMOS, as well as the capability to drive 10 LS-TTL loads.

The 74HC logic family is functionally and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

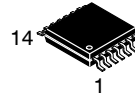
Features

- Typical Propagation Delay: 12 ns
- Wide Power Supply Range: 2 V – 6 V
- Low Quiescent Current: 40 μ A maximum (74HC Series)
- Low Input Current: 1 μ A Maximum
- Fanout of 10 LS-TTL Loads
- Typical Hysteresis Voltage: 0.9 V at $V_{CC} = 4.5$ V
- These Devices are Pb-Free, Halide Free and are RoHS Compliant

Logic Diagram

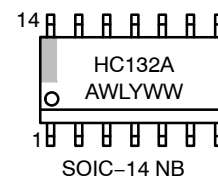


SOIC-14 NB
CASE 751A-03

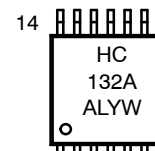


TSSOP-14 WB
CASE 948G

MARKING DIAGRAM



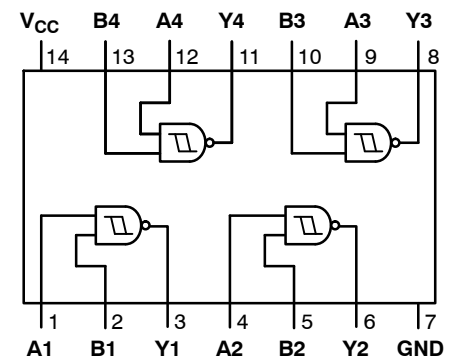
SOIC-14 NB



TSSOP-14 WB

HC132A = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week

CONNECTION DIAGRAM Pin Assignments for SOIC and TSSOP



(Top View)

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MM74HC132

ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Parameter		Rating
V_{CC}	Supply Voltage		-0.5 to +7.0 V
V_{IN}	DC Input Voltage		-0.5 to $V_{CC} + 0.5$ V
V_{OUT}	DC Output Voltage		-0.5 to $V_{CC} + 0.5$ V
I_{IK}, I_{OK}	Clamp Diode Current		±20 mA
I_{OUT}	DC Output Current, per Pin		±25 mA
I_{CC}	DC V_{CC} or GND Current, per Pin		±50 mA
T_{STG}	Storage Temperature Range		-65°C to +150°C
P_D	Power Dissipation	Note 2	600 mW
		S.O. Package Only	500 mW
T_L	Lead Temperature (Soldering 10 Seconds)		260°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.
2. Power Dissipation temperature derating – plastic “N” package: -12 mW/°C from 65°C to 85°C.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage	2	6	V
V_{IN}, V_{OUT}	DC Input or Output Voltage	0	V_{CC}	V
T_A	Operating Temperature Range	-55	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

MM74HC132

DC CHARACTERISTICS (Note 3)

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = 25°C		T _A = -40°C	T _A = -55°C	Unit
				Typ	Guaranteed Limits			
V _{T+} min	Positive Going Threshold Voltage	2.0		-	1.0	1.0	1.0	V
		4.5		-	2.0	2.0	2.0	
		6.0		-	3.0	3.0	3.0	
V _{T+} max		2.0		-	1.5	1.5	1.5	V
		4.5		-	3.15	3.15	3.15	
		6.0		-	4.2	4.2	4.2	
V _{T-} min	Negative Going Threshold Voltage	2.0		-	0.3	0.3	0.3	V
		4.5		-	0.9	0.9	0.9	
		6.0		-	1.2	1.2	1.2	
V _{T-} max		2.0		-	1.0	1.0	1.0	V
		4.5		-	2.2	2.2	2.2	
		6.0		-	3.0	3.0	3.0	
V _H min	Hysteresis Voltage	2.0		-	0.2	0.2	0.2	V
		4.5		-	0.4	0.4	0.4	
		6.0		-	0.5	0.5	0.5	
V _H max		2.0		-	1.0	1.0	1.0	V
		4.5		-	1.4	1.4	1.4	
		6.0		-	1.5	1.5	1.5	
V _{OH}	Minimum HIGH Level Output Voltage	2.0	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA	2.0	1.9	1.9	1.9	V
		4.5		4.5	4.4	4.4	4.4	
		6.0		6.0	5.9	5.9	5.9	
		4.5	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA	4.2	3.98	3.84	3.7	
		6.0		5.7	5.48	5.34	5.2	
V _{OL}	Maximum LOW Level Output Voltage	2.0	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 20 μA	0	0.1	0.1	0.1	V
		4.5		0	0.1	0.1	0.1	
		6.0		0	0.1	0.1	0.1	
		4.5	V _{IN} = V _{IH} or V _{IL} , I _{OUT} ≤ 4.0 mA	0.2	0.26	0.33	0.4	
		6.0		0.2	0.26	0.33	0.4	
I _{IN}	Maximum Input Current	6.0	V _{IN} = V _{CC} or GND	-	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current	6.0	V _{IN} = V _{CC} or GND, I _{OUT} = 0 μA	-	2.0	20	40	μA

3. For a power supply of 5 V ±10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

MM74HC132

AC CHARACTERISTICS ($V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $C_L = 15\text{ pF}$, $t_r = t_f = 6\text{ ns}$)

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Unit
t_{PHL} , t_{PLH}	Maximum Propagation Delay		12	20	ns

AC CHARACTERISTICS ($V_{CC} = 2.0\text{ V to }6.0\text{ V}$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$ (unless otherwise specified))

Symbol	Parameter	V_{CC} (V)	Conditions	$T_A = 25^\circ\text{C}$		$T_A = -40^\circ\text{C}$ to 85°C	$T_A = -55^\circ\text{C}$ to 125°C	Unit
				Typ	Guaranteed Limits			
t_{PHL} , t_{PLH}	Maximum Propagation Delay	2.0		63	125	158	186	ns
		4.5		13	25	32	37	
		6.0		11	21	27	32	
t_{TLH} , t_{THL}	Maximum Output Rise and Fall Time	2.0		30	75	95	110	ns
		4.5		8	15	19	22	
		6.0		7	13	16	19	
C_{PD}	Power Dissipation Capacitance (Note 4)		(per gate)	130	-		-	pF
C_{IN}	Maximum Input Capacitance			-	5	10	10	pF

4. C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

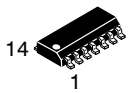
ORDERING INFORMATION

Part Number	Package	Shipping [†]
MM74HC132M	SOIC-14, Case 751A-03 (Pb-Free, Halide Free)	55 Units / Tube
MM74HC132MTC	TSSOP-14, Case 948G-01 (Pb-Free, Halide Free)	96 Units / Tube
MM74HC132MX	SOIC-14, Case 751A-03 (Pb-Free, Halide Free)	2500 / Tape & Reel
MM74HC132MTCX	TSSOP-14 WB, Case 948G-01 (Pb-Free, Halide Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NOTE: Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

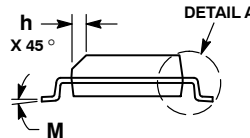
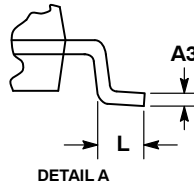
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. NO CONNECTION
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 2:
 CANCELLED

STYLE 3:
 PIN 1. NO CONNECTION
 2. ANODE
 3. ANODE
 4. NO CONNECTION
 5. ANODE
 6. NO CONNECTION
 7. ANODE
 8. ANODE
 9. ANODE
 10. NO CONNECTION
 11. ANODE
 12. ANODE
 13. NO CONNECTION
 14. COMMON CATHODE

STYLE 4:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. CATHODE
 4. NO CONNECTION
 5. CATHODE
 6. NO CONNECTION
 7. CATHODE
 8. CATHODE
 9. CATHODE
 10. NO CONNECTION
 11. CATHODE
 12. CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 5:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. COMMON ANODE
 8. COMMON CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 6:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE
 4. CATHODE
 5. CATHODE
 6. CATHODE
 7. CATHODE
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 14. ANODE

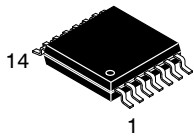
STYLE 7:
 PIN 1. ANODE/CATHODE
 2. COMMON ANODE
 3. COMMON CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. COMMON CATHODE
 12. COMMON ANODE
 13. ANODE/CATHODE
 14. ANODE/CATHODE

STYLE 8:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. COMMON ANODE
 8. COMMON ANODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. NO CONNECTION
 12. ANODE/CATHODE
 13. ANODE/CATHODE
 14. COMMON CATHODE

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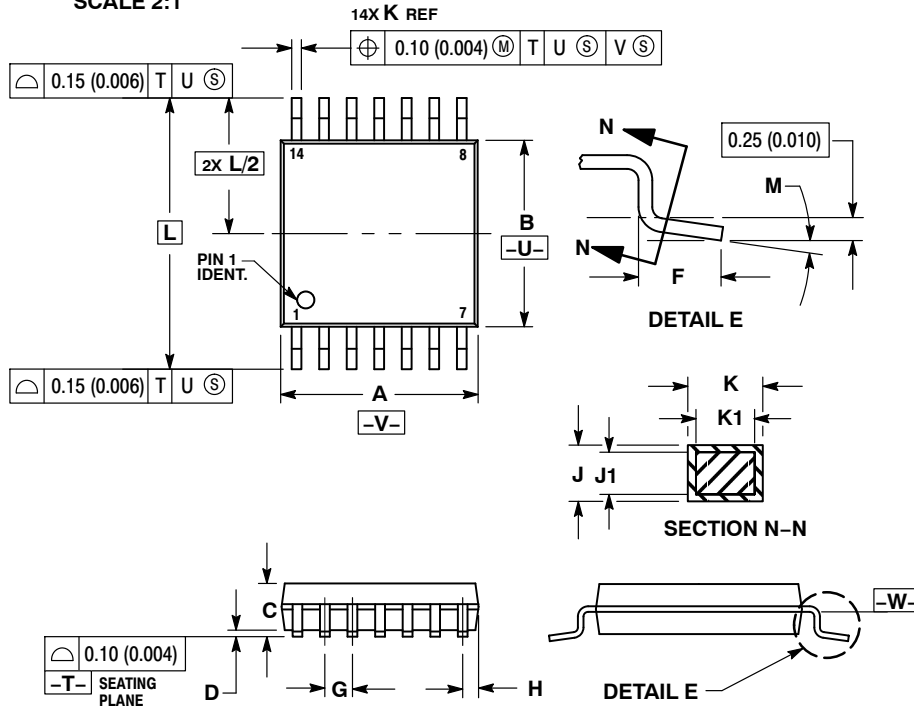
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-14 WB
CASE 948G
ISSUE C

DATE 17 FEB 2016

SCALE 2:1

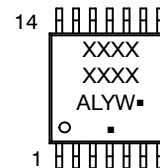


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM*

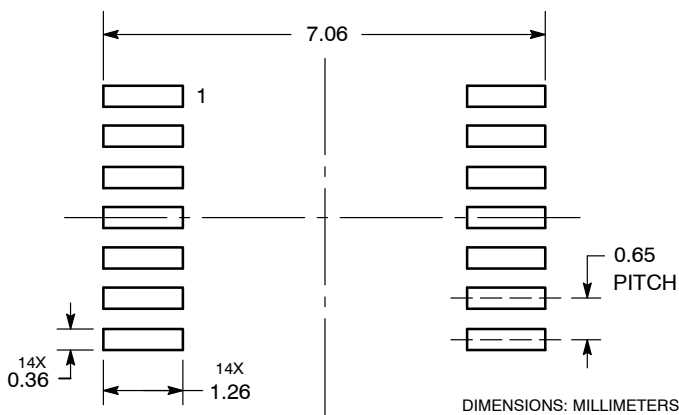


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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